Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit	
Collector-emitter voltage	V _{CEO}	50	V	
Output withstand voltage	V _{CE (SUS)}	50	V	
Output current	I _{OUT} 500		mA	
Input voltage	V _{IN}	-0.5~30	V	
Clamp diode reverse voltage	V _R	50	V	
Clamp diode forward current	١ _F	500	mA	
Power dissipation	P _D (Note 4)	0.78	W	
Saturated thermal resistance	R _{th (j-a)} (Note 4)	160	°C/W	
	R _{th (j-c)} (Note 5)	25	0/00	
Operating temperature	T _{opr}	opr -40~85		
Storage temperature	T _{stg}	-55~150	°C	

Note 4: $114.3 \times 76.2 \times 1.6$ mm glass epoxy film substrate Cu heat dissipation pattern 100 mm²

Note 5: When an infinite heat sink is mounted.

Recommended Operating Condition (Ta = -40~85°C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit	
Output withstand voltage		V _{CEO}	—	0		50	V	
Output current		I _{OUT}	$Ta = 60^{\circ}C, T_{j} = 105^{\circ}C$	_	_	220	mA	
Input voltage		V _{IN}		0	_	24	V	
Input voltage	Output ON	V _{IN (ON)}	I _{OUT} = 400 mA, h _{FE} = 800	2.8	_	24	v	
	Output OFF	V _{IN (OFF)}		0	_	0.7		
Clamp diode reverse voltage		V _R		_		50	V	
Clamp diode forward current		١ _F	—	_		350	mA	

Electrical Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Circuit	Test Condition		Min	Тур.	Max	Unit
Output leakage current		ICEX	1	$V_{CE} = 50 \text{ V}, \text{ V}_{IN} = \text{OPEN}$			_	10	μA
Output saturation voltage		V _{CE (sat)}	2	$I_{OUT} = 300 \text{ mA}, I_{IN} = 500 \mu\text{A}$			1.1	1.3	v
				$I_{OUT} = 200 \text{ mA}, I_{IN} = 350 \mu\text{A}$		_	1.0	1.2	
DC current amplification ratio		h _{FE}	2	$V_{CE} = 2.0 \text{ V}, \text{ I}_{OUT} = 350 \text{ mA}$		1000	_	_	
Input current	Output ON	I _{IN (ON)}	3	$V_{IN} = 2.4 \text{ V}, I_{OUT} = 350 \text{ mA}$			0.4	0.7	mA
Input voltage	Output ON	Vin (ON)	4	V _{CE} = 2 V, h _{FE} = 800	I _{OUT} = 350 mA		_	2.6	V
	Output ON				$I_{OUT} = 200 \text{ mA}$		_	2.2	
Clamp diode leakage current		I _R	5	V _R = 50 V		_	_	10	μA
Clamp diode forward voltage		VF	6	I _F = 350 mA		_	1.6	2.0	V
Turn-on delay		t _{ON}	7	$\label{eq:VOUT} \begin{array}{l} V_{OUT} = 50 \ V, \ R_L = 125 \ \Omega, \\ C_L = 15 \ pF \end{array}$			0.02	_	μs
Turn-off delay		tOFF	/				1.0	_	

TOSHIBA

Test Circuit

1. I_{CEX}

2. V_{CE (sat)} h_{FE}













6. V_F







7. ton, toff



Caution on Application

- The device does not include protectors such as an overcurrent protector and an overvoltage protector. Applying excessive current or voltage may damage the device. Thus, design with great care to prevent excessive current or voltage from being applied to the device. The device may also be damaged by short-circuits between outputs and power supply/ground. Take care when designing output, VCC and GND line.
- 2. Be sure to mount the device in the correct orientation. Make sure that the positive and negative power supply pins are connected the right way round. Otherwise, the absolute maximum current and power dissipation ratings may be exceeded and the device may break down or undergo performance degradation, causing it to catch fire or explode, and resulting in injury.

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Package Dimensions

2

Weight: 0.017 g (typ.)

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Preliminary land pattern



Preliminary PCB trace dimension



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